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FIG. 1A

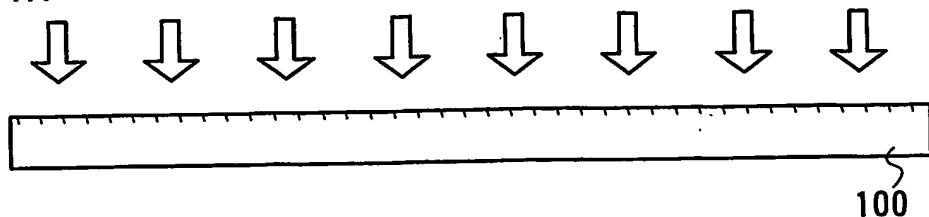


FIG. 1B

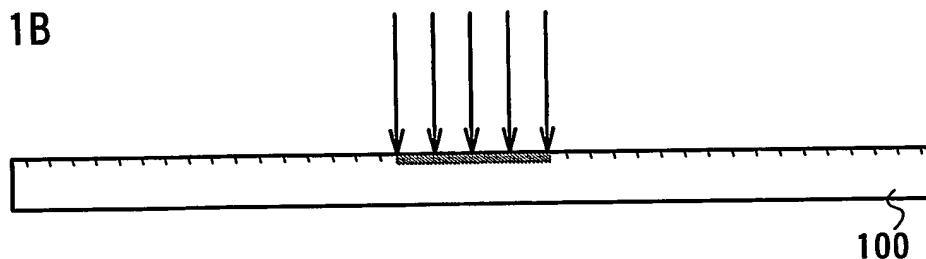


FIG. 1C

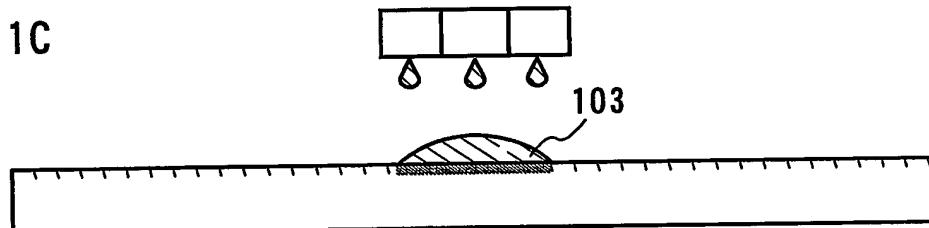


FIG. 1D

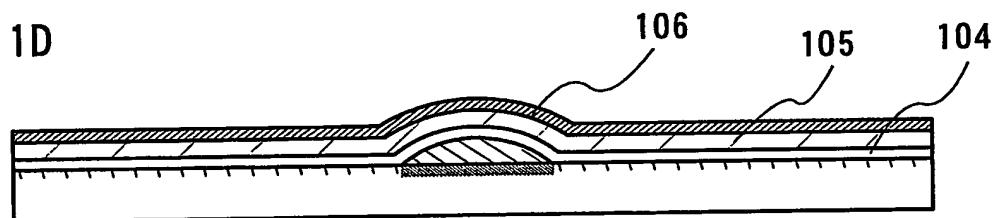


FIG. 1E

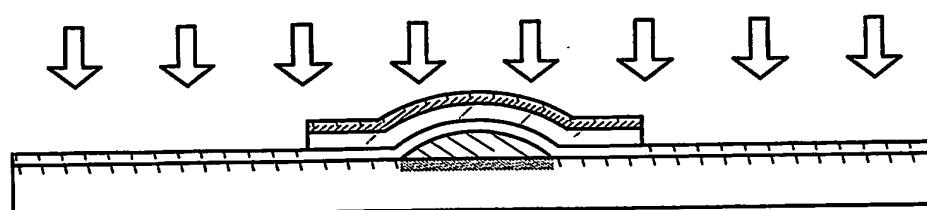
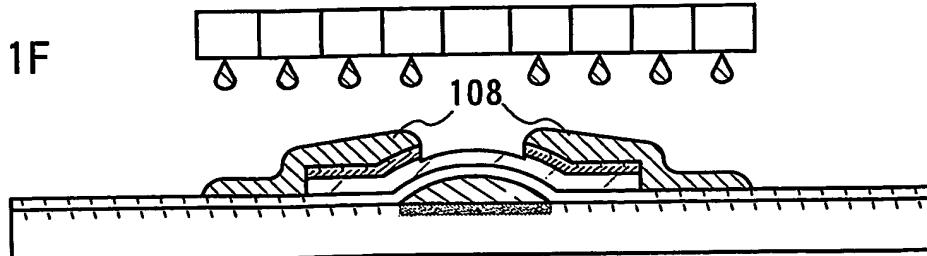


FIG. 1F



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FIG. 2A

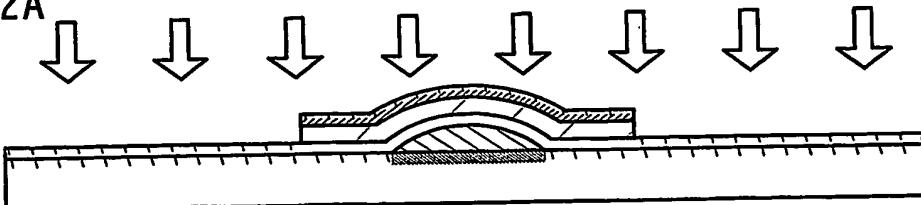


FIG. 2B

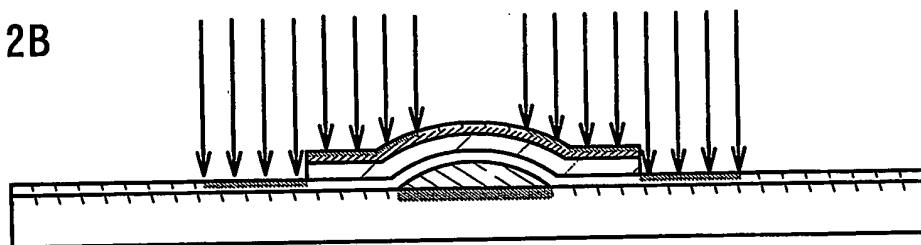
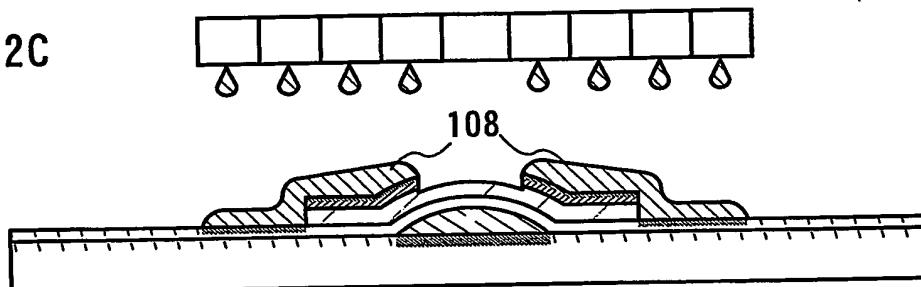


FIG. 2C



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FIG. 3A

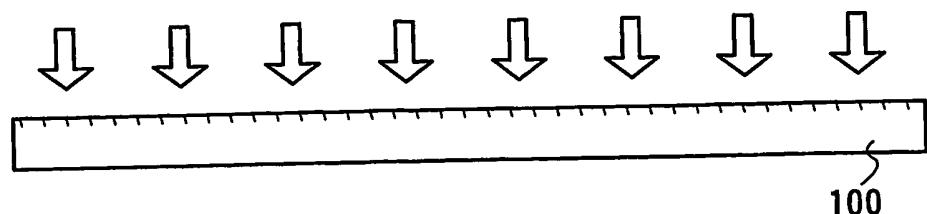


FIG. 3B

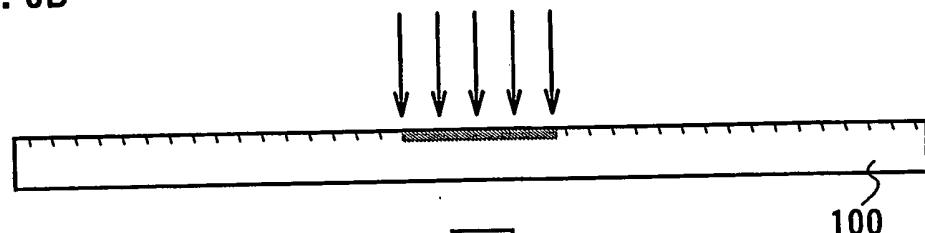


FIG. 3C

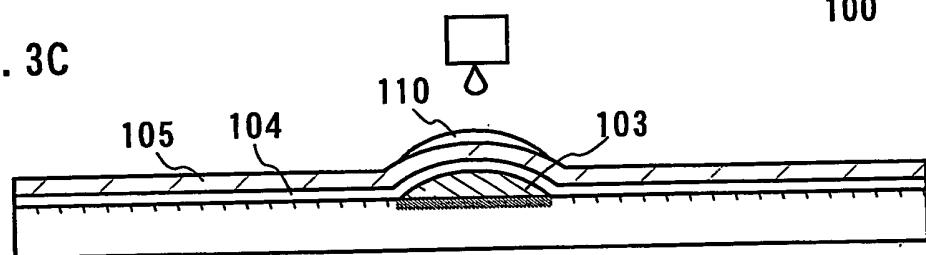


FIG. 3D

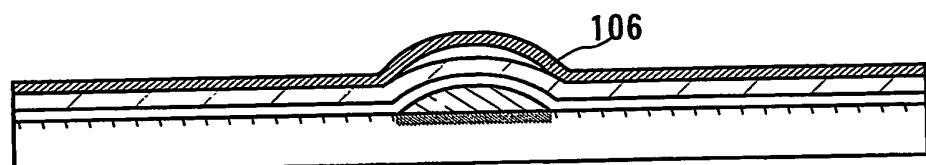


FIG. 3E

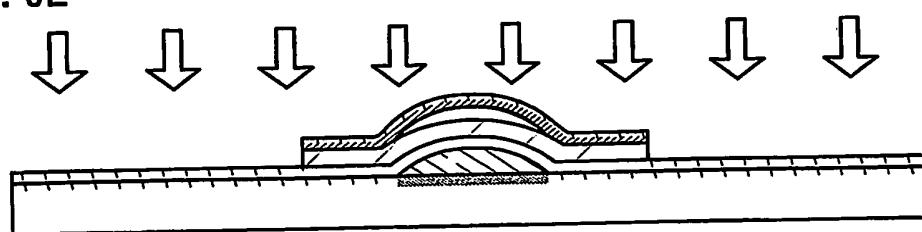
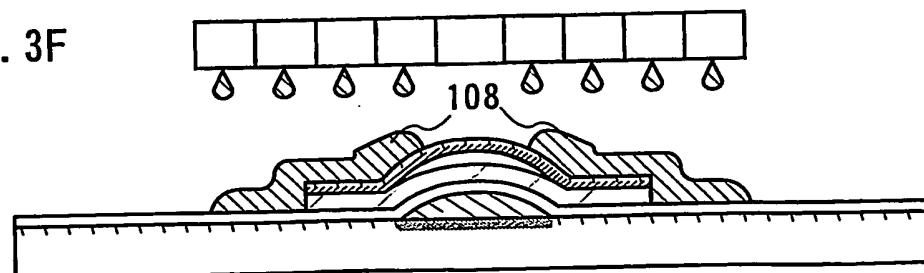


FIG. 3F



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FIG. 4A

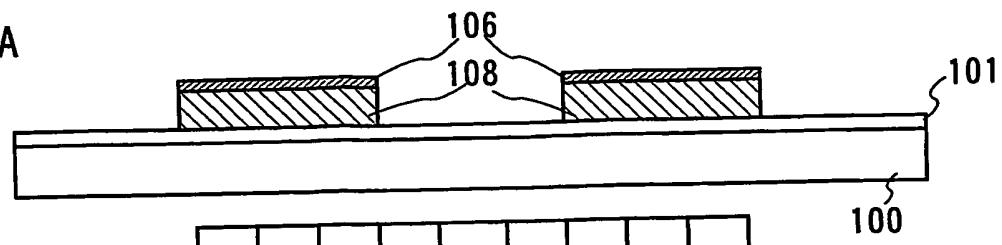


FIG. 4B

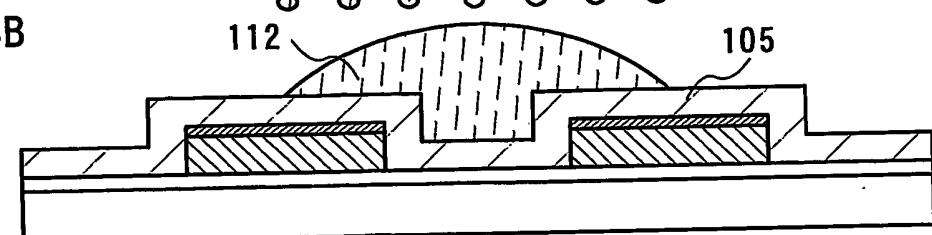


FIG. 4C

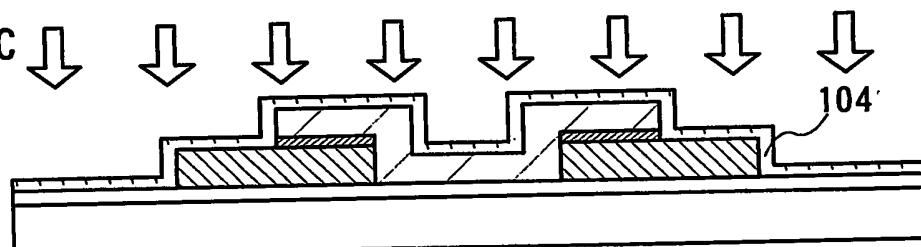


FIG. 4D

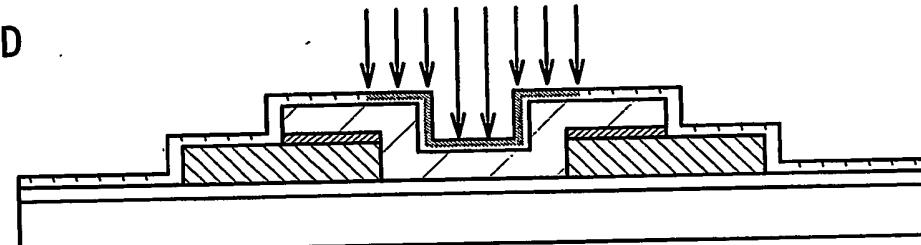


FIG. 4E

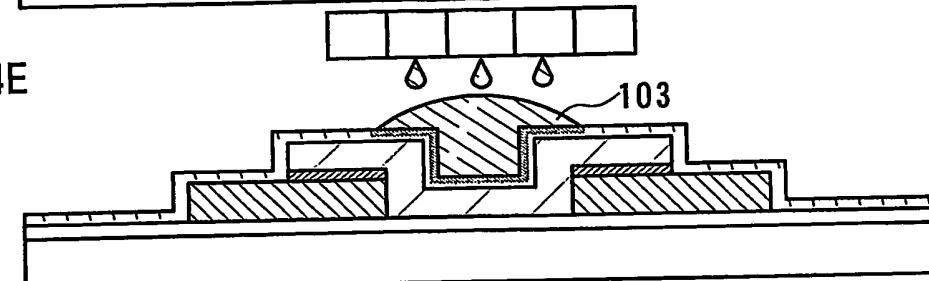
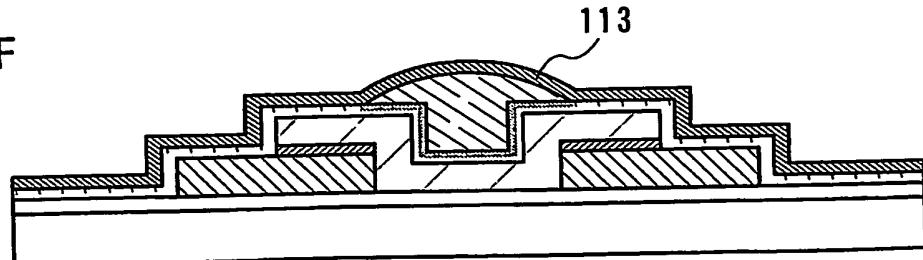
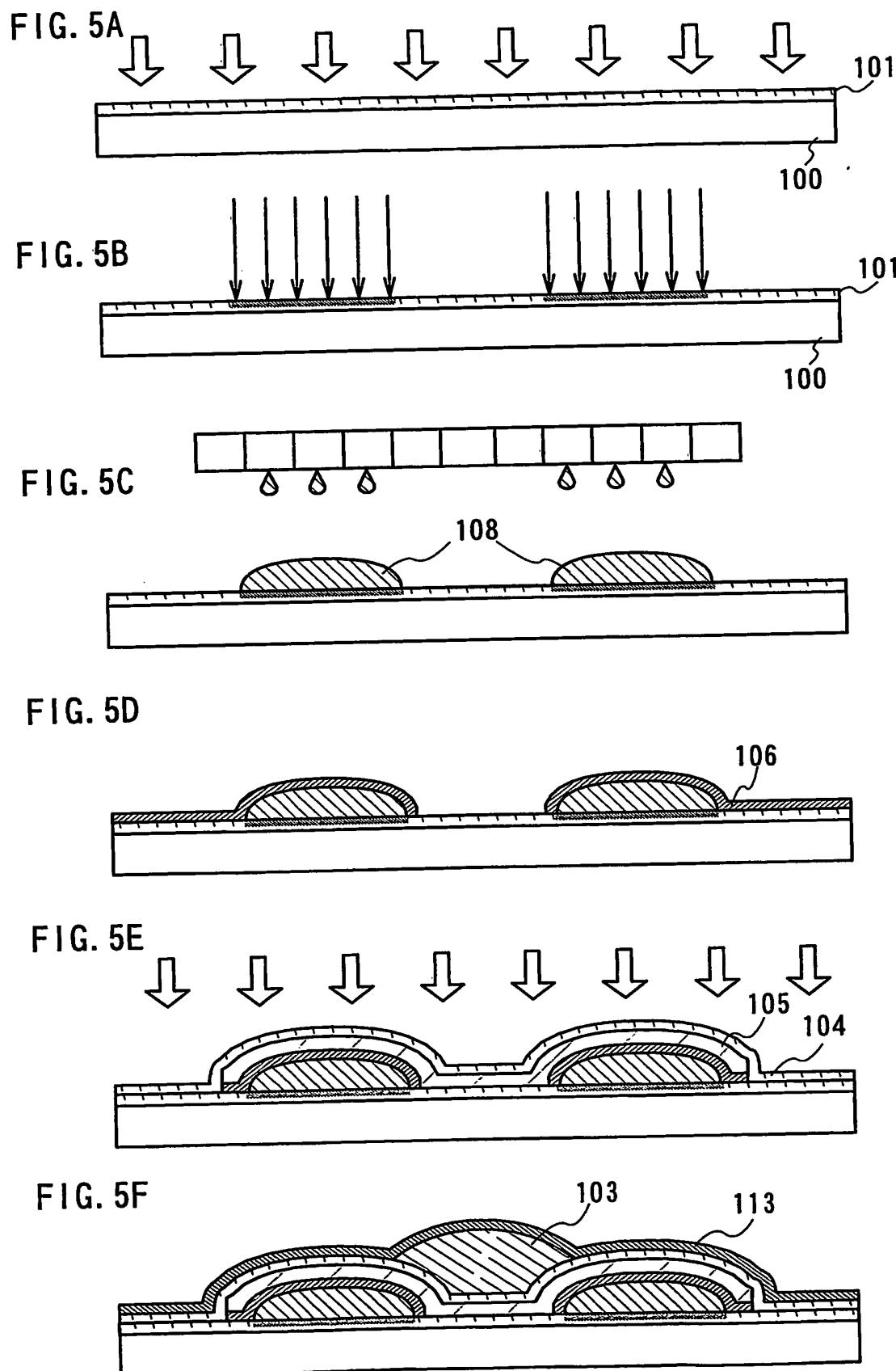


FIG. 4F



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FIG. 6A

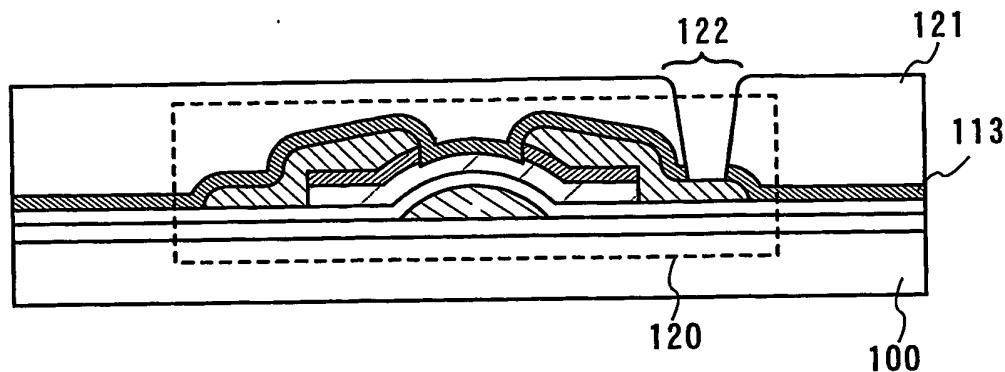


FIG. 6B

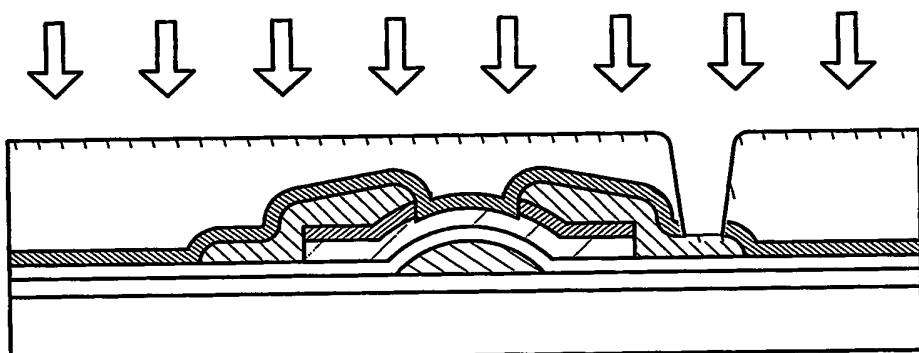


FIG. 6C

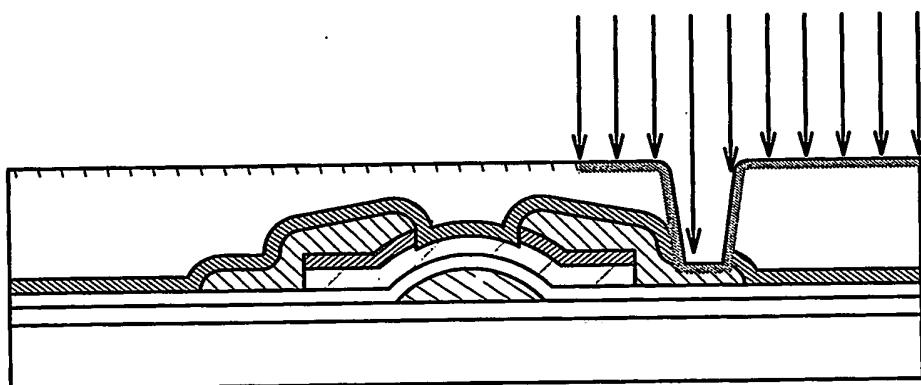
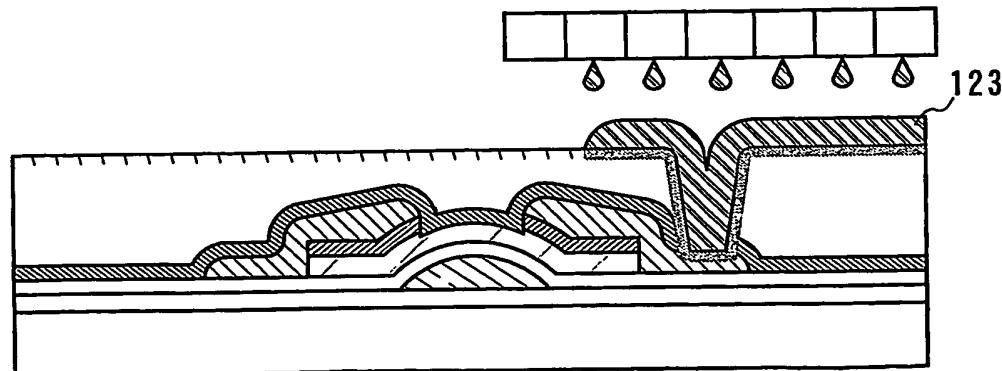


FIG. 6D



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FIG. 7A

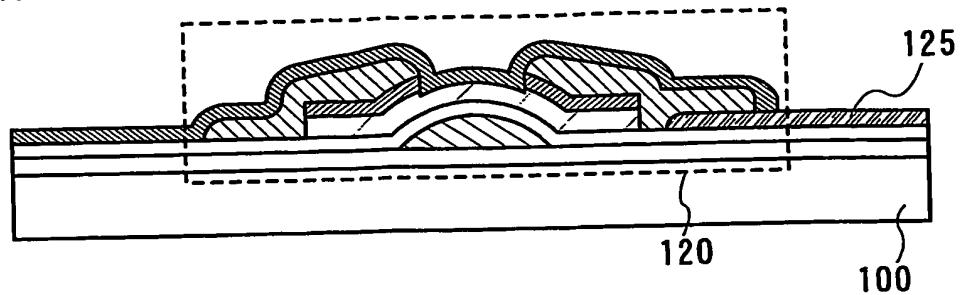


FIG. 7B

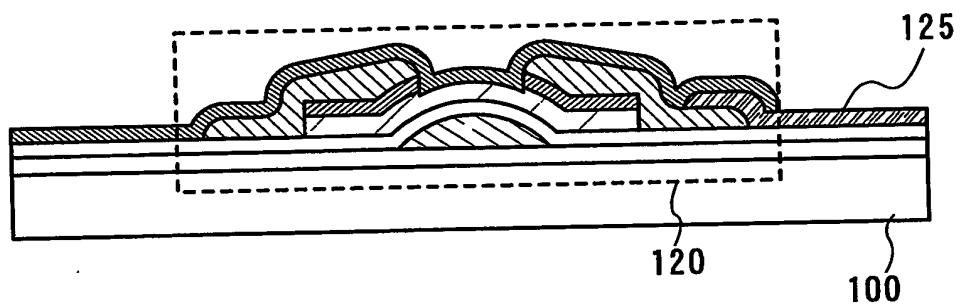
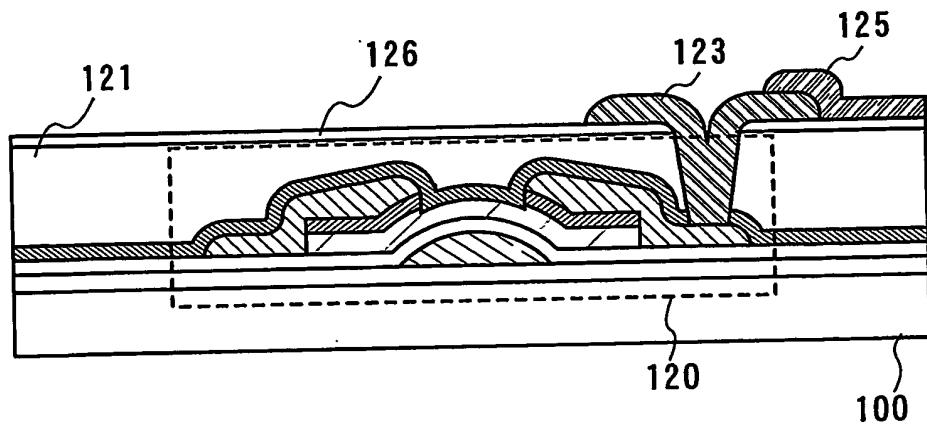
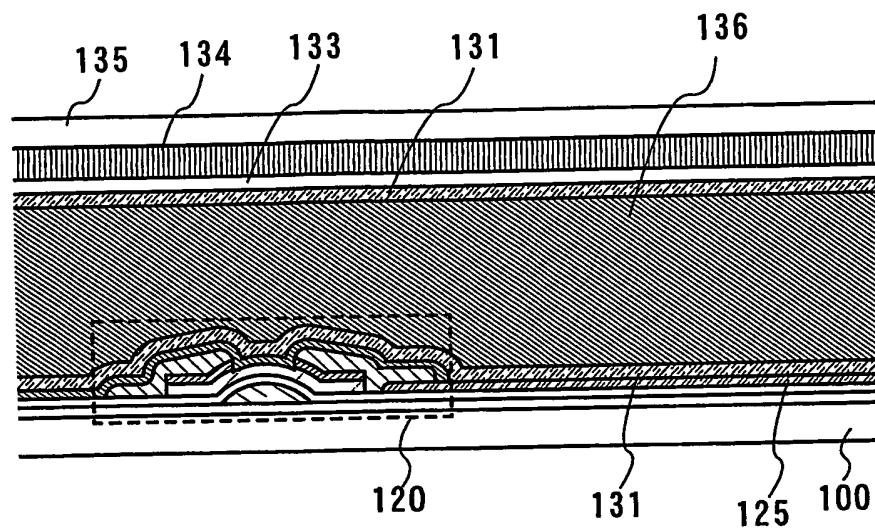


FIG. 7C



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FIG. 8

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FIG. 9A

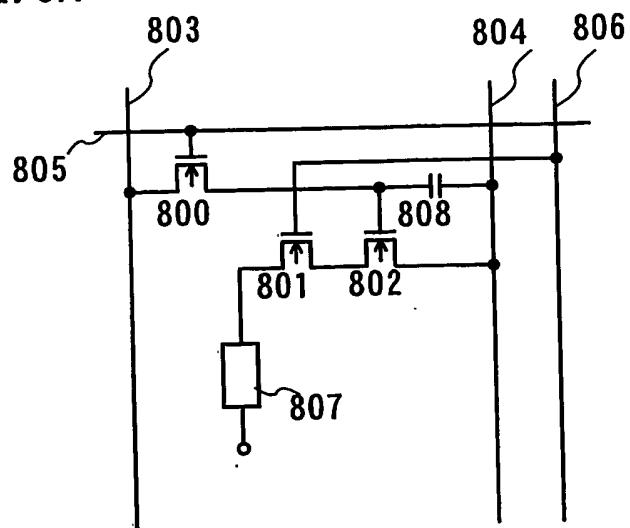
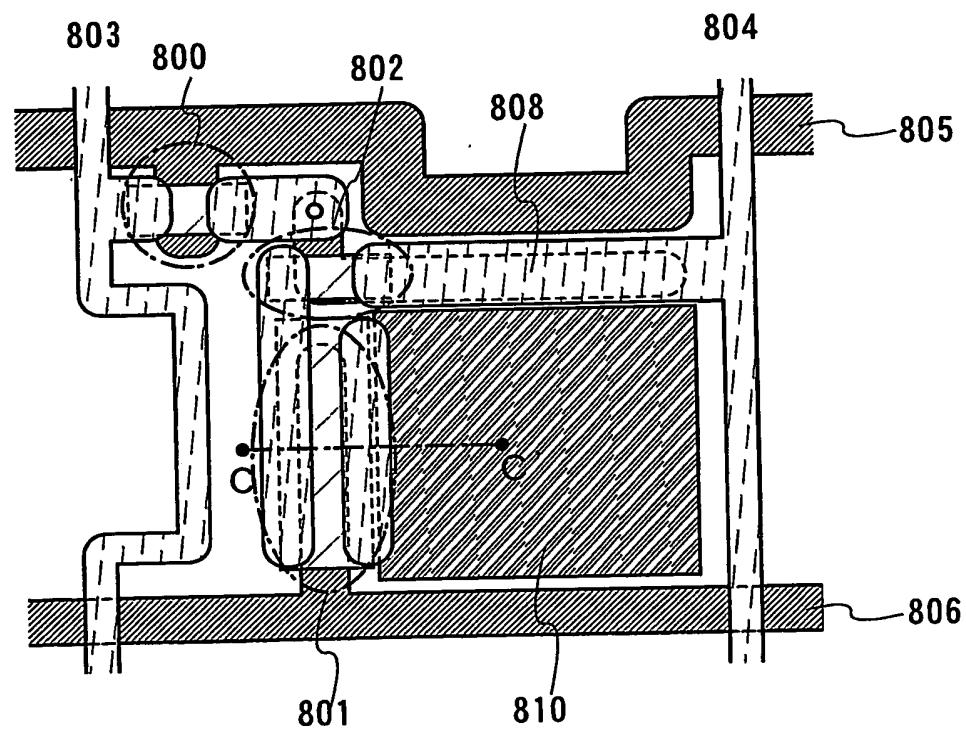
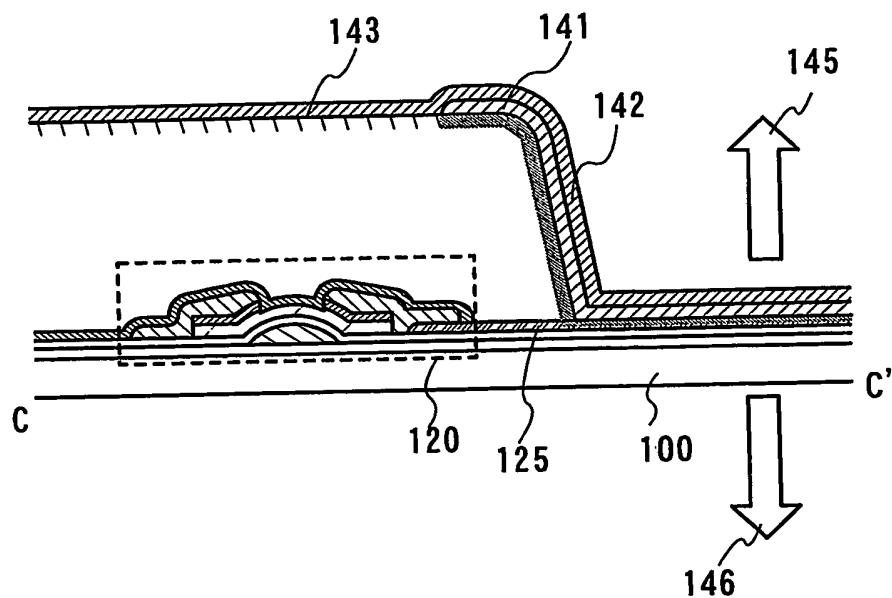
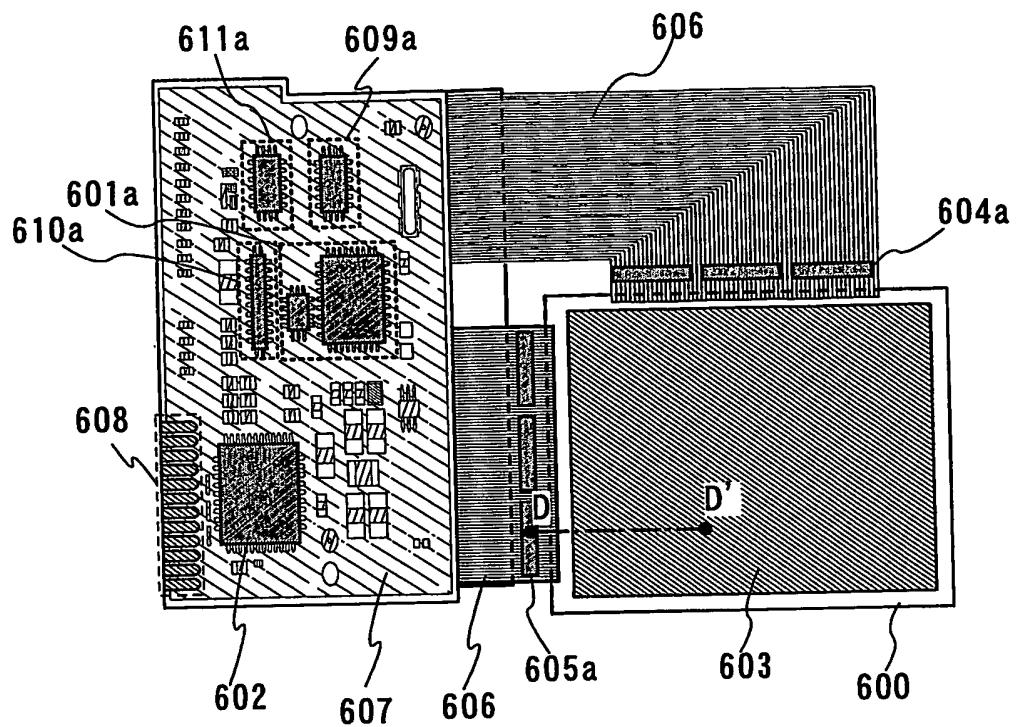


FIG. 9B



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FIG. 10

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FIG. 11

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FIG. 12A

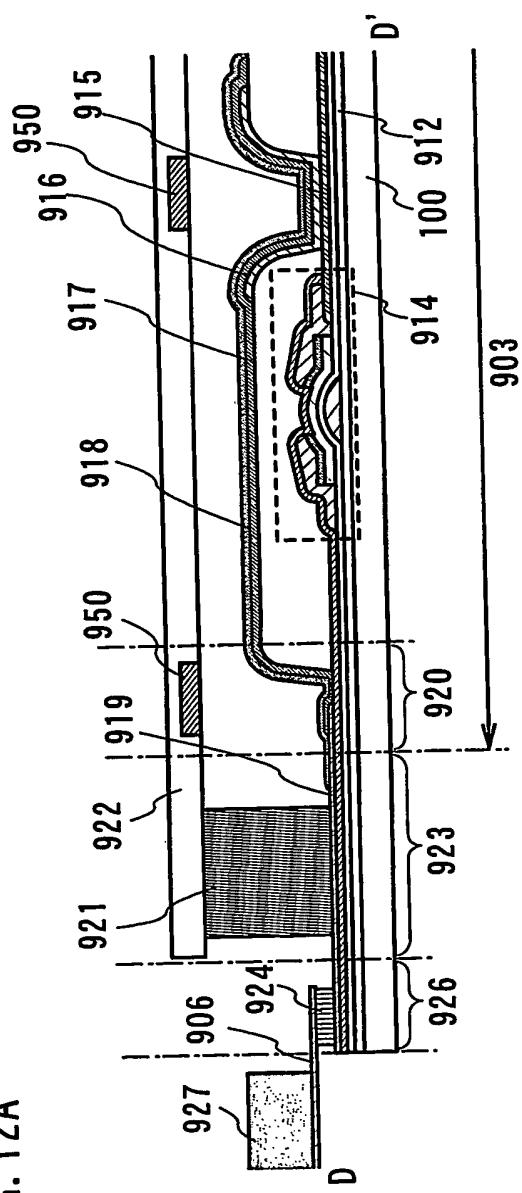
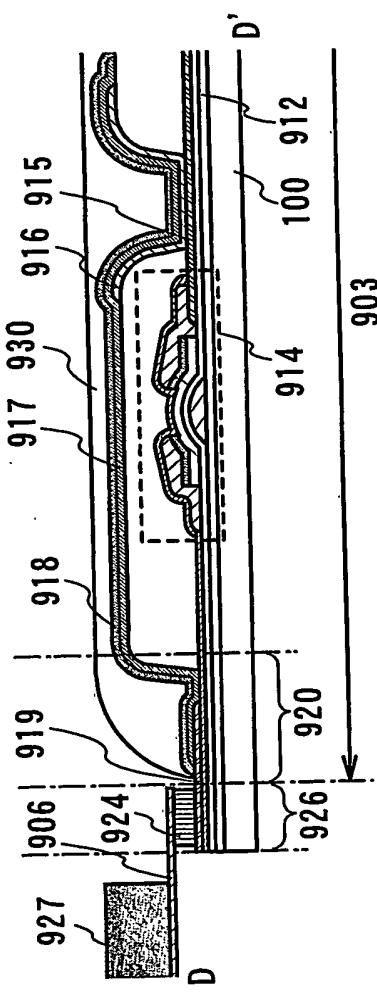


FIG. 12B



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FIG. 13A

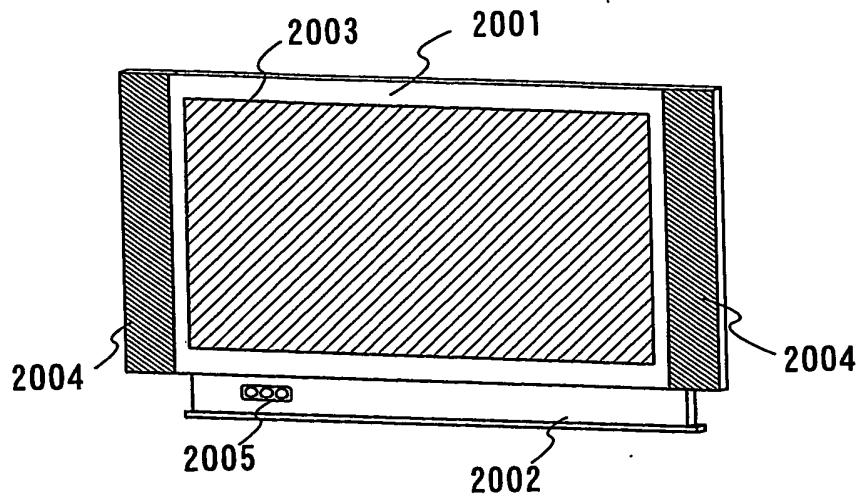


FIG. 13B

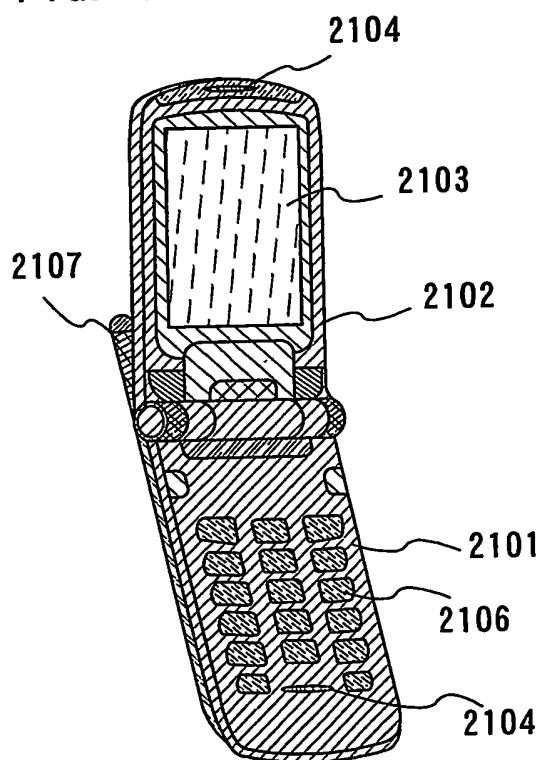
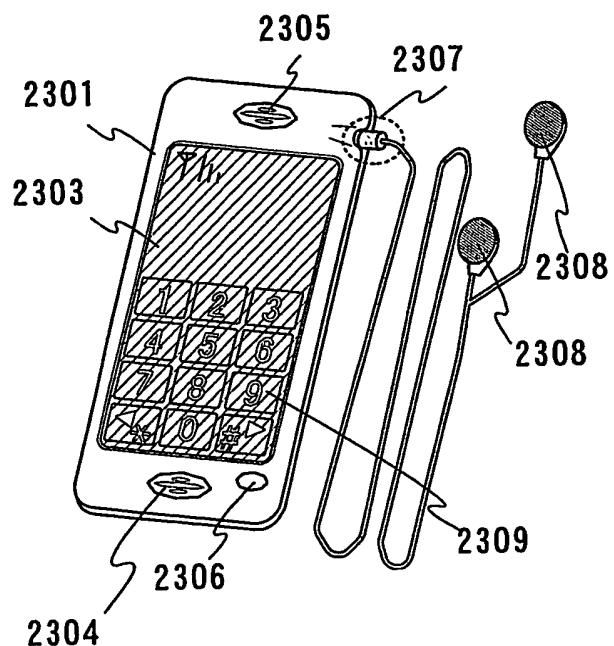


FIG. 13C



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FIG. 14A

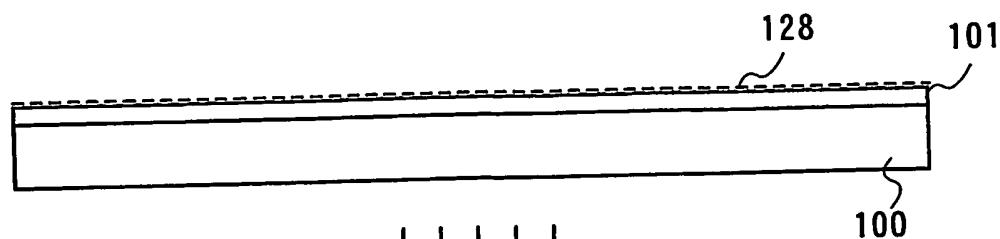


FIG. 14B

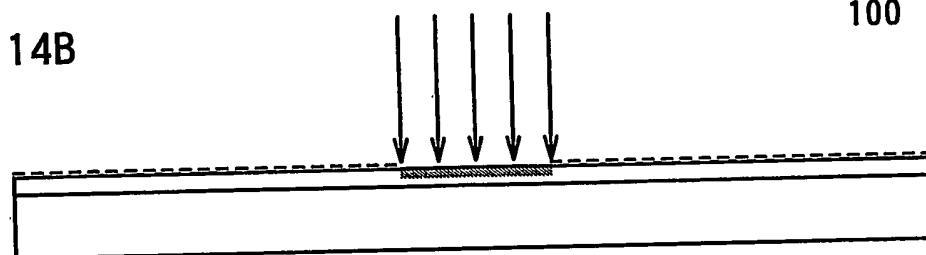


FIG. 14C

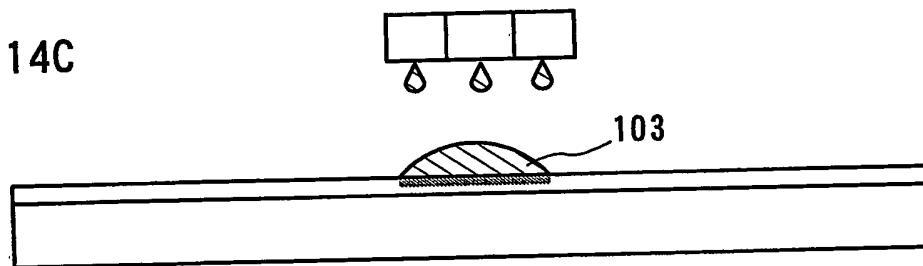
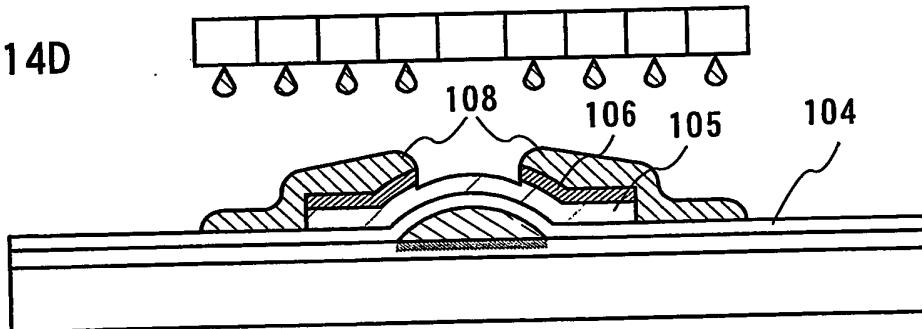


FIG. 14D



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FIG. 15A

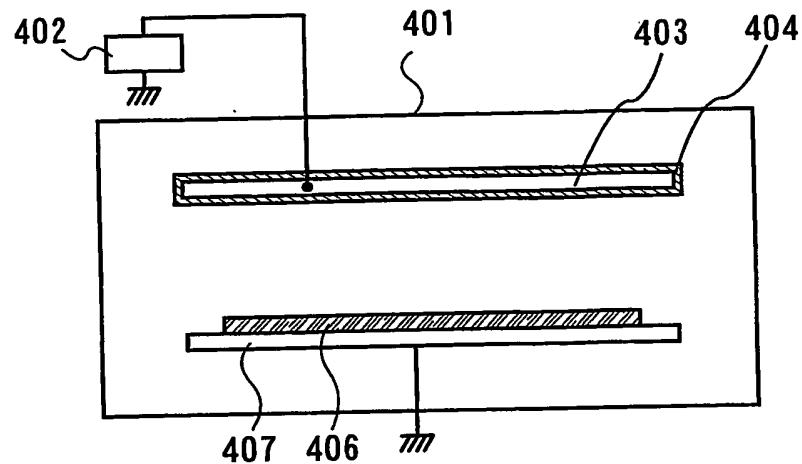
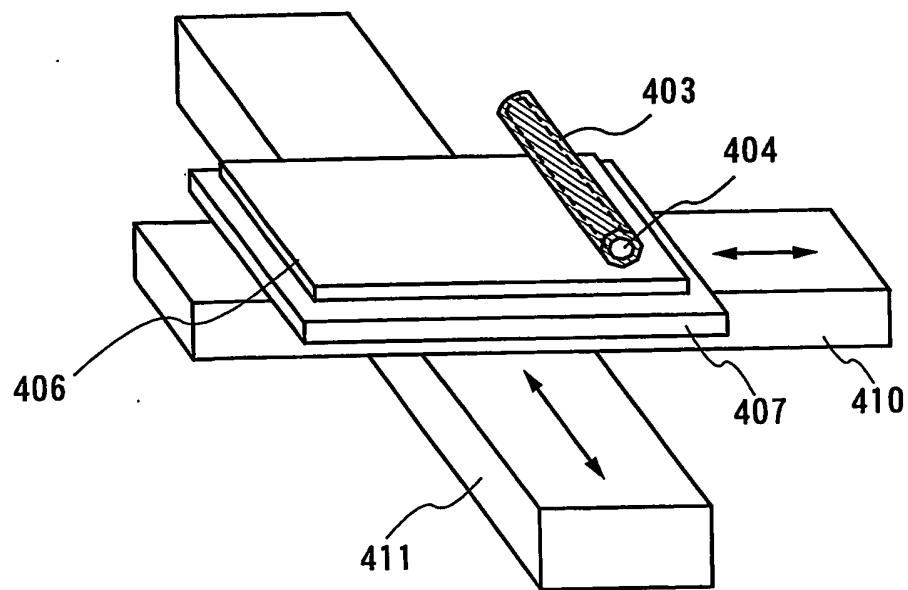
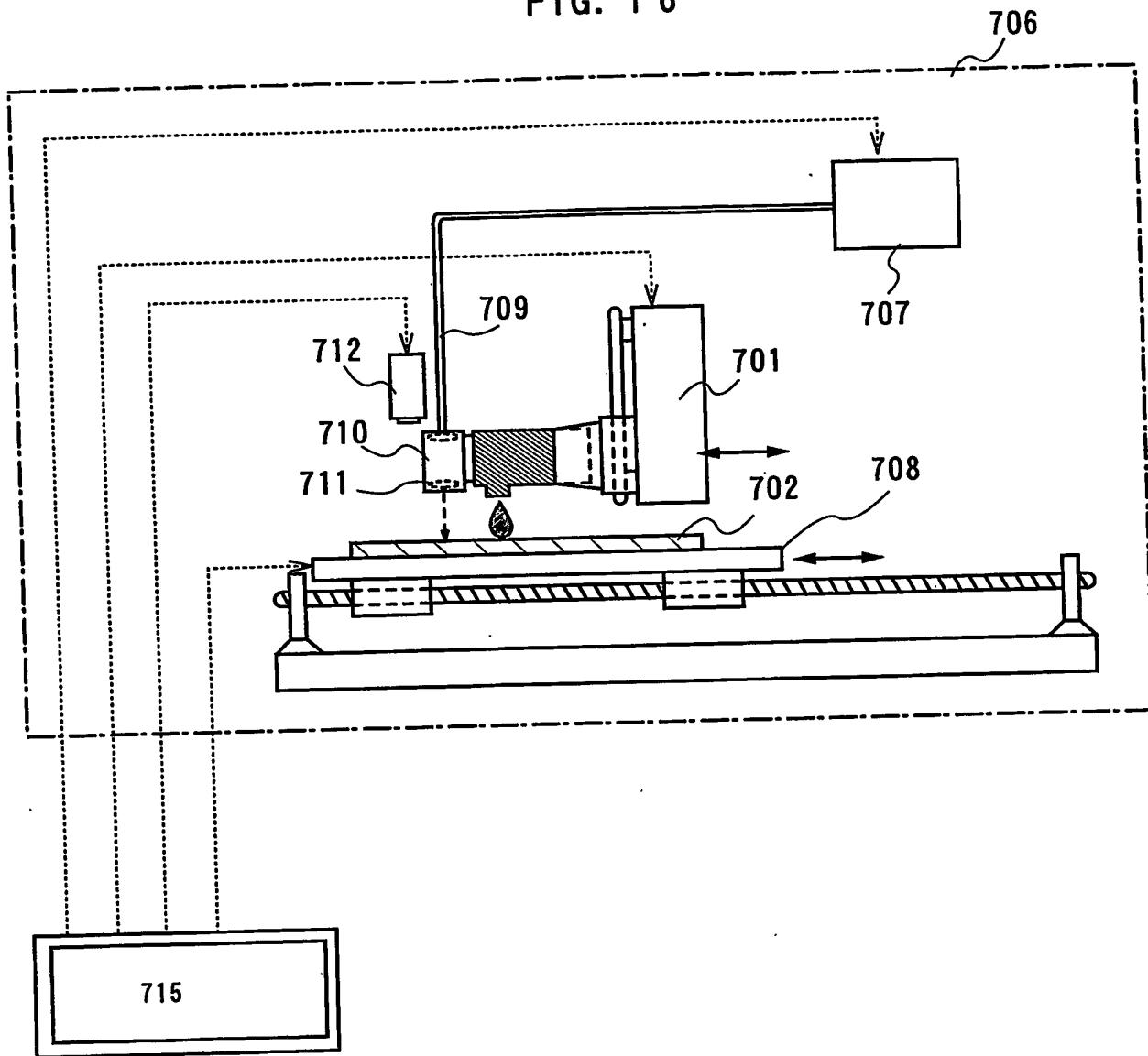


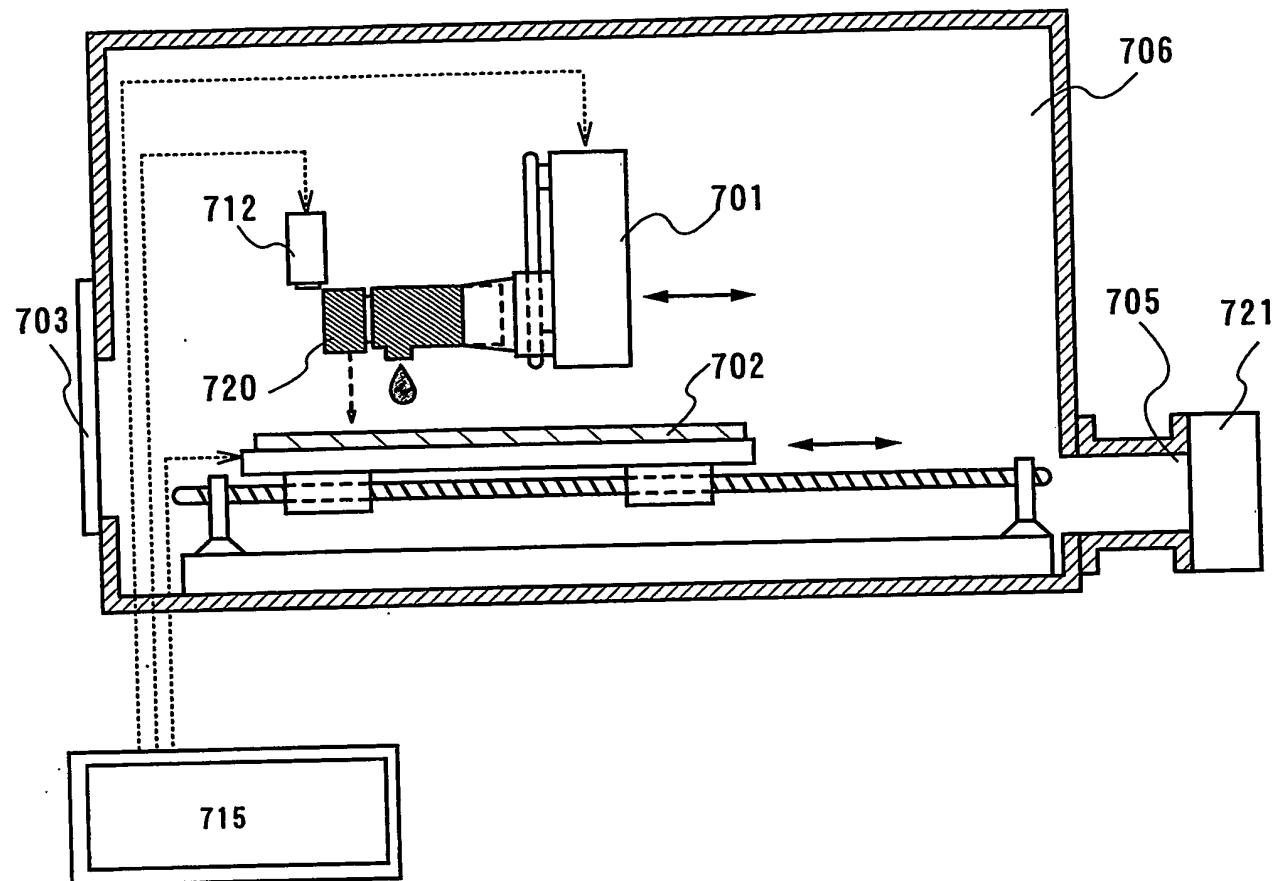
FIG. 15B



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FIG. 16



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FIG. 17



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FIG. 18A

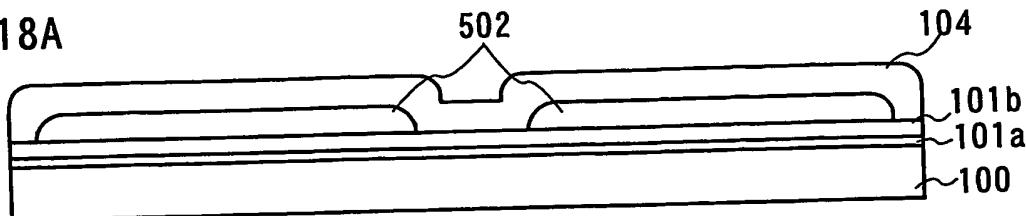


FIG. 18B

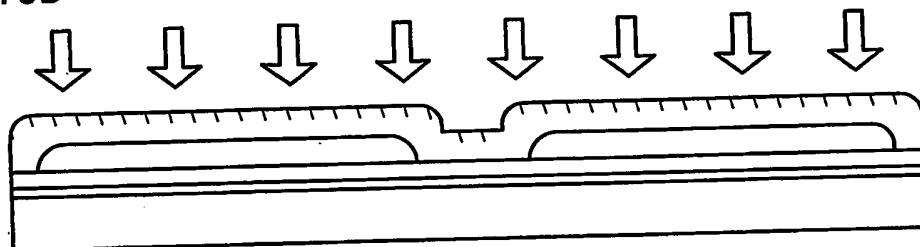


FIG. 18C

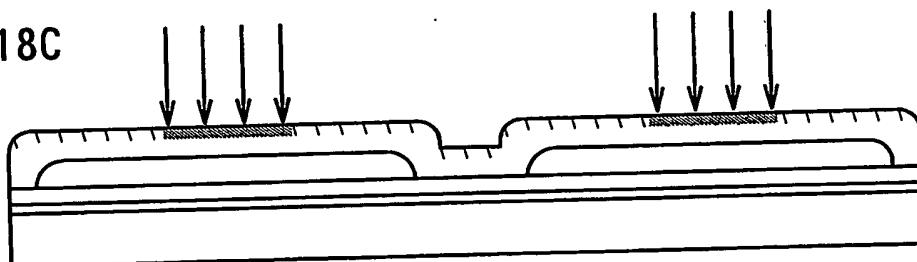


FIG. 18D

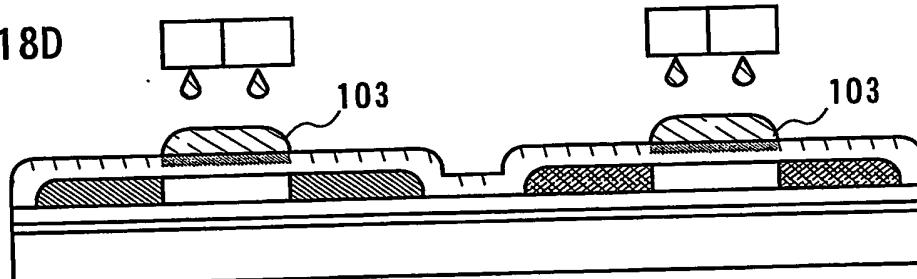
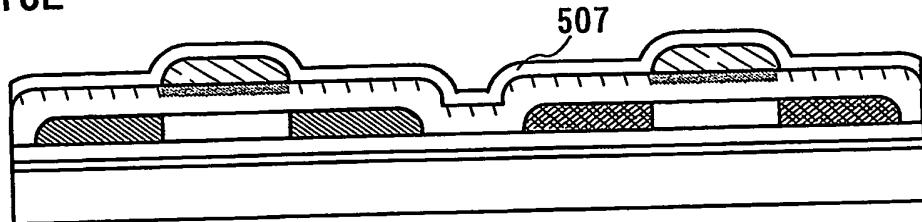


FIG. 18E



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FIG. 19A

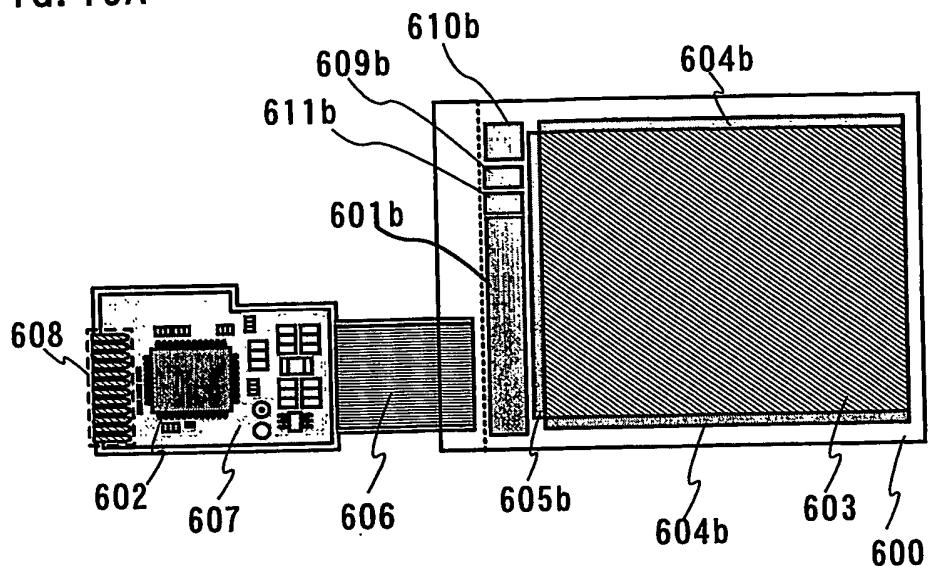
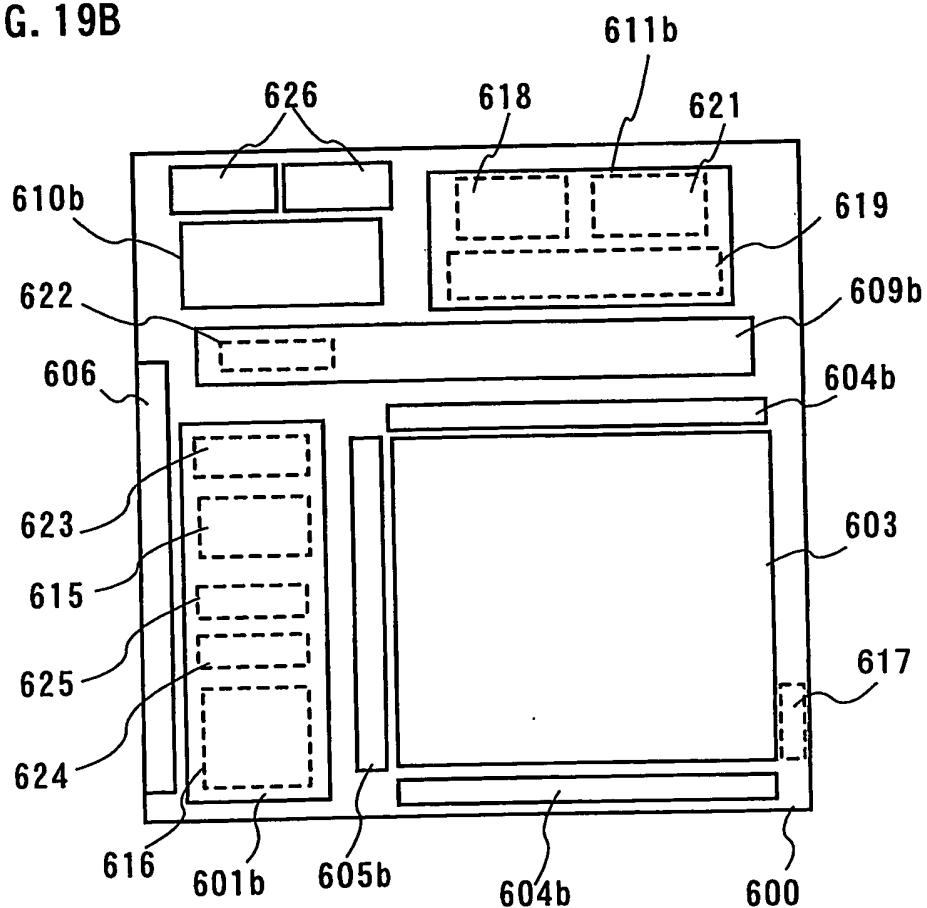
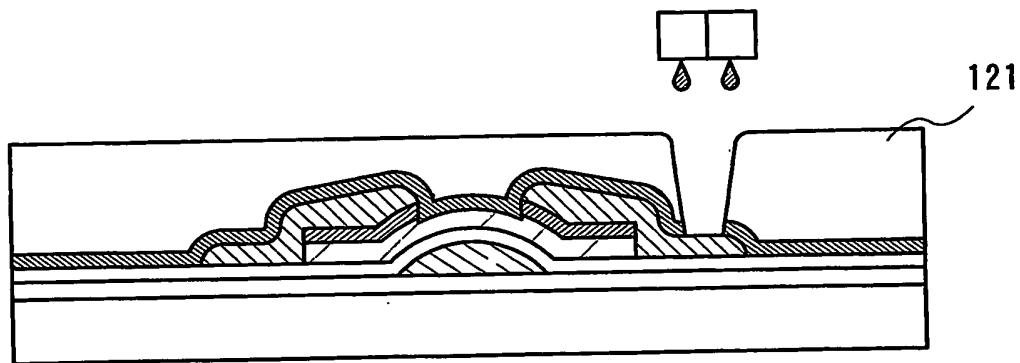


FIG. 19B



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FIG. 20



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FIG. 21A

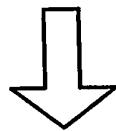
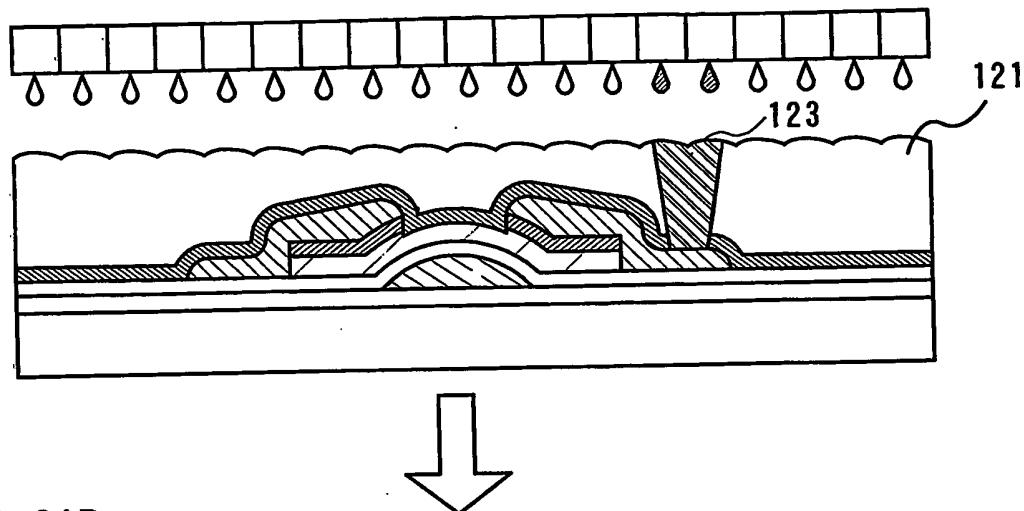
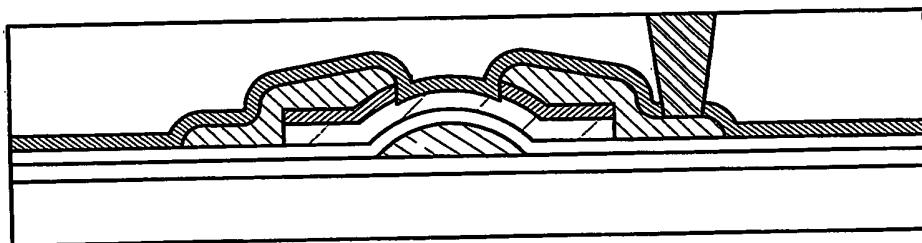


FIG. 21B



## EXPLANATION OF REFERENCE

100 substrate, 101 base film, 103 gate electrode, 104 gate insulating film, 105 semiconductor film, 106 semiconductor film, 108 drain electrode, 110 protective film, 112 mask, 113 protective film, 101a base film, 101b base film, 201b silicon oxynitride film, 502 semiconductor film, 507 insulating film, 401 treatment chamber, 403 electrode, 404 dielectric, 402 power supply, 406 substrate, 407 stage, 410 uniaxial robot, 411 uniaxial robot, 706 treatment chamber, 701 droplet discharging unit, 702 object to be treated, 708 stage (transport stage), 712 CCD camera, 707 laser oscillator, 708 stage, 715 central processing unit, 709 fiber, 710 terminal, 711 lens, 705 exhaust port, 721 pressure reduction apparatus, 703 transport port, 128 Teflon film, 120 TFT, 121 interlayer insulating film, 122 opening portion, 123 wiring, 120 thin film transistor, 125 pixel electrode, 126 insulating film, 131 orientation film, 135 opposite substrate, 134 color filter, 133 opposite electrode, 136 liquid crystal layer, 143 insulating film, 141 electroluminescent layer, 142 electrode, 125 electrode, 145 directions of both arrows, 146 direction of arrow, 145 direction of arrow, 800 TFT (switching TFT), 801 TFT (driving TFT), 802 TFT (current controlling TFT), 800 switching TFT, 803 signal line, 805 scanning line, 802 current controlling TFT, 804 power supply line, 808 capacitor element, 801 driving TFT, 806 power supply line, 807 light emitting element, 810 electrode, 601a control circuit, 602 power supply circuit, 600 substrate, 603 pixel portion, 604a scanning line driver circuit, 605a signal line driver circuit, 607 printed wiring board, 609a image signal processing circuit, 610a video RAM, 611a audio circuit, 606 FPC, 608 interface (I/F) portion, 604b scanning line driver circuit, 605b signal line driver circuit, 601b control circuit, 611b audio circuit, 609b image signal processing circuit, 609b video RAM, 617 gray-scale power supply, 616 CPU, 623 CPU interface (I/F),

624 WRAM, 615 PROM, 625 memory controller, 619 audio ROM, 621 audio controller,  
618 amplifier, 622 CRAM, 626 SRAM, 903 pixel portion, 912 base film, 914 driving TFT,  
915 anode, 916 electroluminescent layer, 917 cathode, 918 protective film, 920  
connection region, 919 connection wiring, 923 sealing region, 921 sealing material, 911  
5 substrate, 925 desiccant agent, 926 connection region, 927 IC chip, 924 anisotropic  
conductive film, 906 FPC, 922 substrate, 930 protective film, 2001 chassis, 2002  
supporting section, 2003 display portion, 2004 speaker portion, 2005 video input  
terminal, 2101 main body, 2102 chassis, 2103 display portion, 2104 audio input portion,  
2105 audio output portion, 2106 operation key, 2107 antenna, 2301 main body, 2303  
10 display portion, 2304 audio input portion, 2305 audio output portion, 2306 switch, 2307  
external connection port, 2308 earphone, 2309 touch panel operation key